

Ziren Wang

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/6332823/publications.pdf>

Version: 2024-02-01

17
papers

50
citations

2258059

3
h-index

1872680

6
g-index

17
all docs

17
docs citations

17
times ranked

24
citing authors

#	ARTICLE	IF	CITATIONS
1	The Impact of Connection Failure of Bonding Wire on Signal Transmission in Radio Frequency Circuits. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1729-1737.	2.5	9
2	Modeling and Analysis of Signal Integrity of High-Speed Interconnected Channel With Degraded Contact Surface. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 2227-2236.	2.5	8
3	Modeling and Analysis of Signal Integrity of Ball Grid Array Packages With Failed Ground Solder Balls. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 306-315.	2.5	7
4	The Impact of Electrical Contact Degradation on Differential Signal Transmission of High Speed Channel. , 2018, , .		4
5	Impedance Compensation of the Welding Area of the RF Connector and Microstrip Line. , 2018, , .		4
6	High-Frequency Behavior Analysis and Modeling of Silver Plated Printed Circuit Board with Electrochemical Migration. Journal of Electronic Materials, 2019, 48, 8039-8046.	2.2	3
7	Study on the Effects of RF Coaxial Connector Degradation on Signal Integrity using S Parameters. , 2019, , .		3
8	Impact of the Ball Grid Array Connection Failures on Signal Integrity. , 2020, , .		3
9	Investigation of impedance compensation in radio frequency circuits with bonding wire. International Journal of RF and Microwave Computer-Aided Engineering, 2022, 32, .	1.2	3
10	Investigations on the Effect of Electrical Contact Degradation on High Speed Wide-Band Signal Integrity. Chinese Journal of Electronics, 2020, 29, 525-532.	1.5	2
11	Intelligent Detection Methods of Electrical Connection Faults in RF Circuits. Applied Sciences (Switzerland), 2021, 11, 9973.	2.5	2
12	Investigation of the improvement of signal integrity in electrical circuits with degraded contacts using differential transmission. IET Circuits, Devices and Systems, 2019, 13, 303-308.	1.4	1
13	Impact of receptacle degradation and loose connection on signal integrity and electrical performance repeatability. IET Circuits, Devices and Systems, 2020, 14, 1012-1017.	1.4	1
14	Symmetry degradation of differential circuits induced by uneven gold plating of high-speed connectors in extreme environment. Microwave and Optical Technology Letters, 2020, 62, 3716-3726.	1.4	0
15	The Impact of Connector Degradation on Signal Transmission in Humid Environment. , 2021, , .		0
16	Impact of Impedance Change Caused by Bonding Wire Connection on Signal Transmission. , 2020, , .		0
17	The Impact of Gold Plating Process for Bonding Pads on Interconnection Quality. IEEE Transactions on Device and Materials Reliability, 2022, , 1-1.	2.0	0